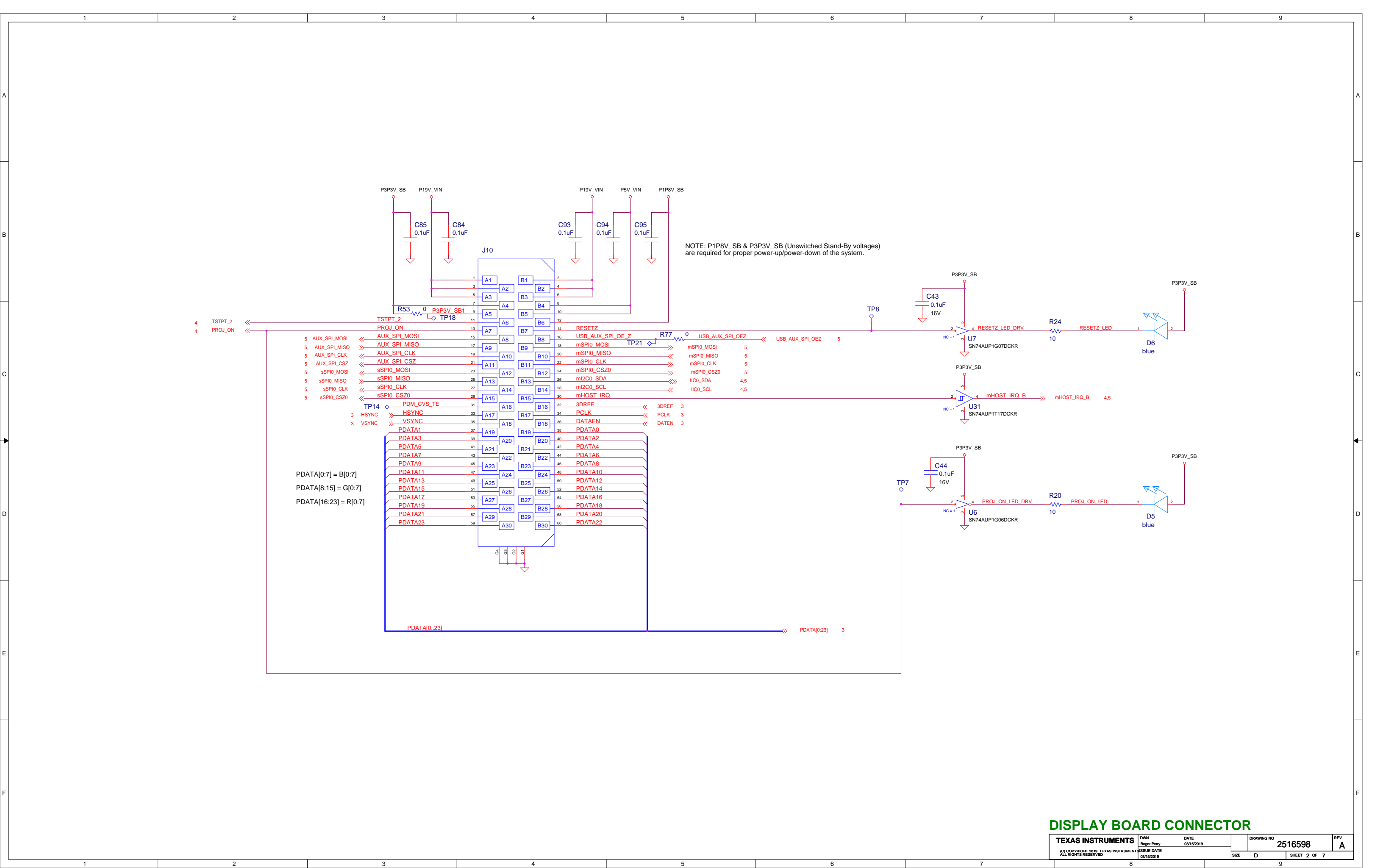


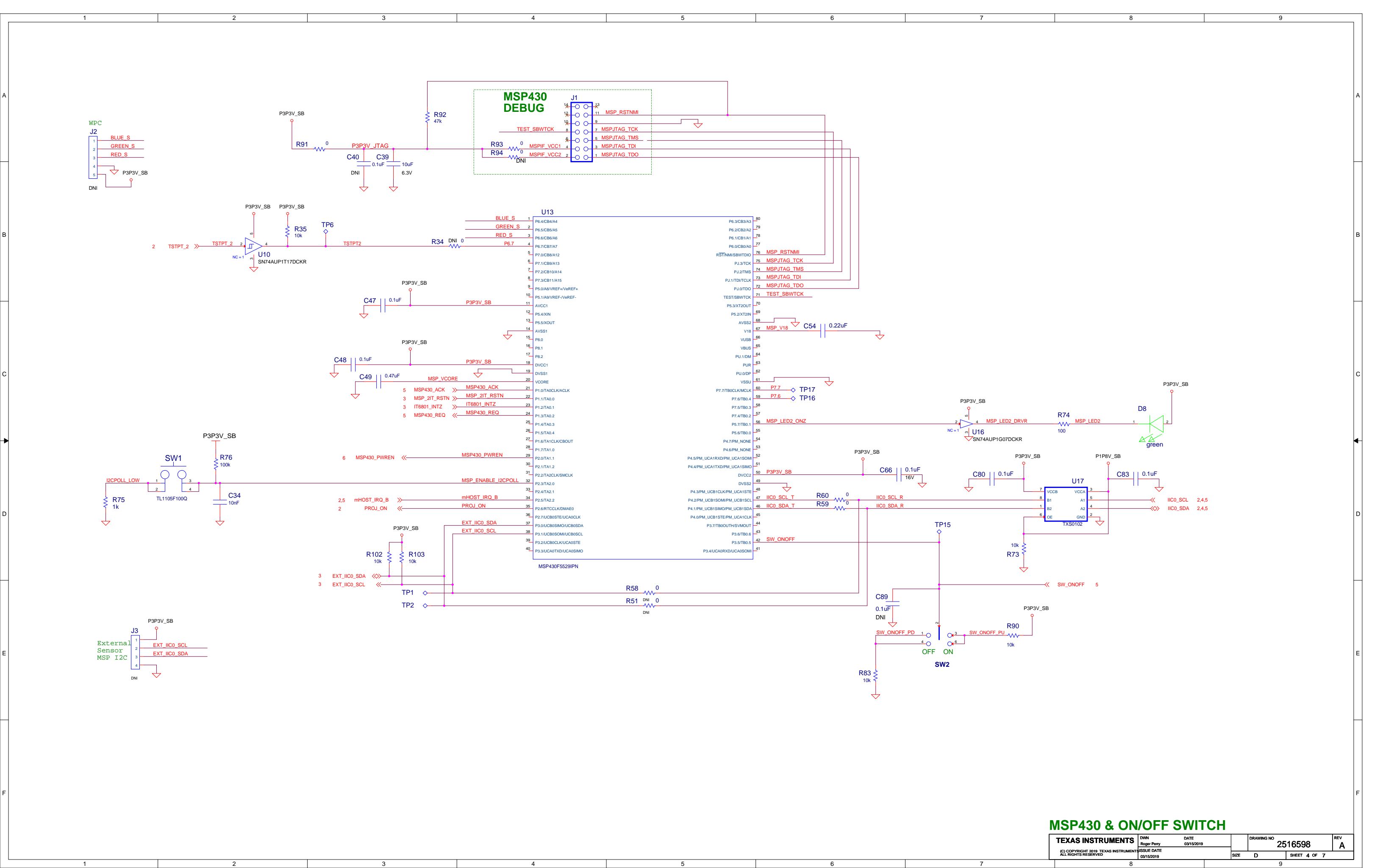
DLPC3436 SYSTEM BOARD
REFERENCE DESIGN

COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY			
REVISIONS			
REV	DESCRIPTION		DATE
A	ECO	INITIAL RELEASE	03/15/2019
			R. PERRY

DWN	Roger Perry	DATE	MAR-15-2019	TEXAS INSTRUMENTS - DLP® Products	
ENGR	Roger Perry	MAR-15-2019		(C) COPYRIGHT 2019 Texas Instruments Inc. All Rights Reserved	
SYS	Dan Morgan	MAR-15-2019		TITLE DLPC3436 System Board Reference Design	
APVD	Jeff Dennis	MAR-15-2019		DRAWING NO	2516598
QA	---	---		REV	A
		11 x 17	Orcad Capture 16.6	SHEET 1	of 7

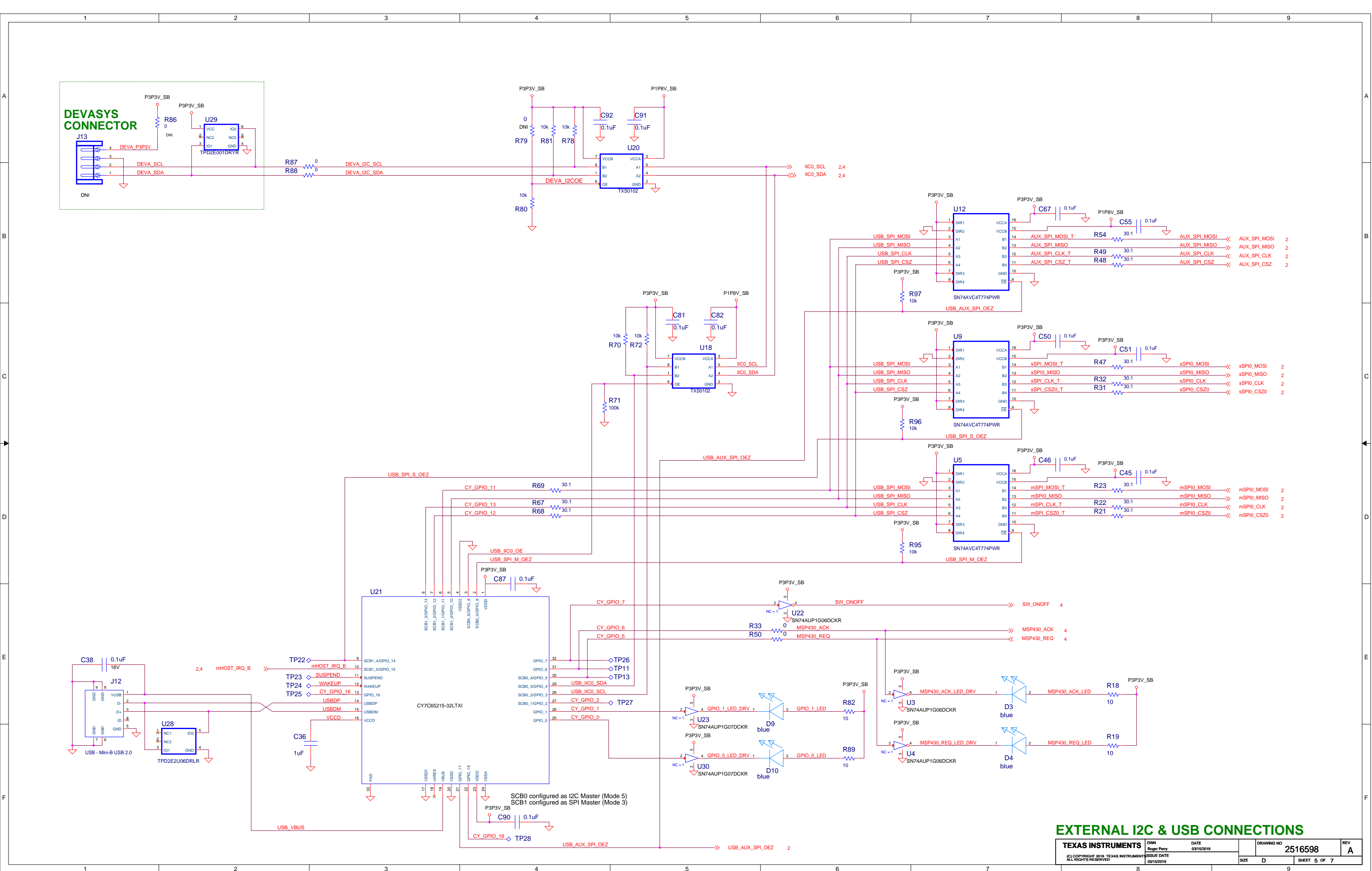


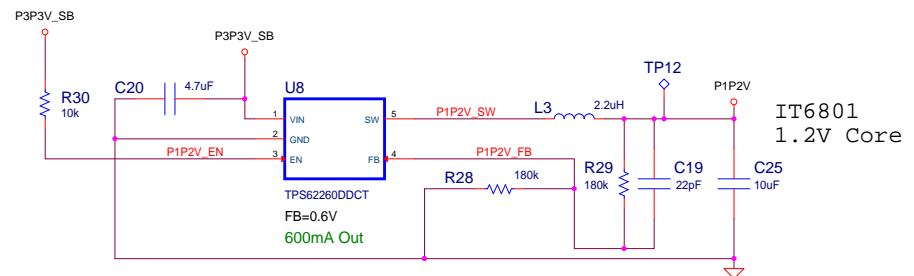
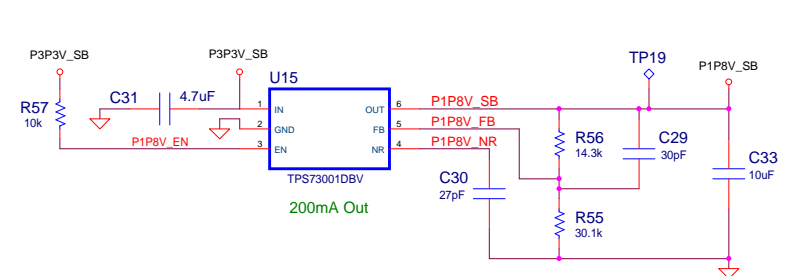
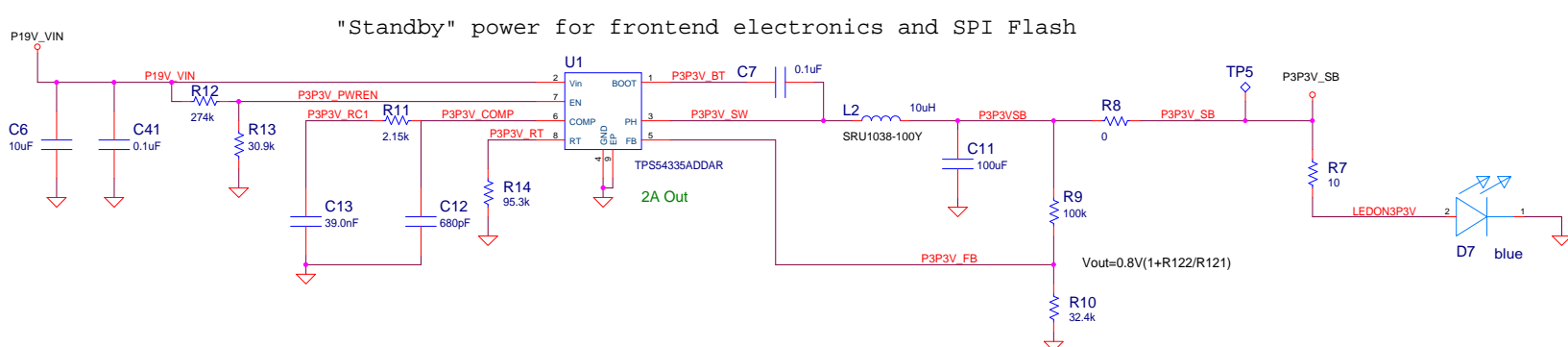
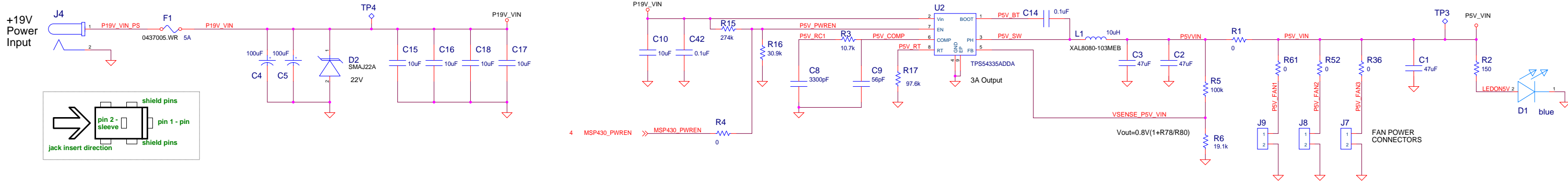
DISPLAY BOARD CONNECTOR



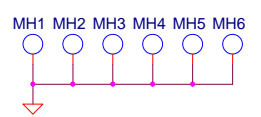
MSP430 & ON/OFF SWITCH

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	SIZE D			





BOARD MOUNTING HOLES



19V INPUT & POWER SUPPLIES

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